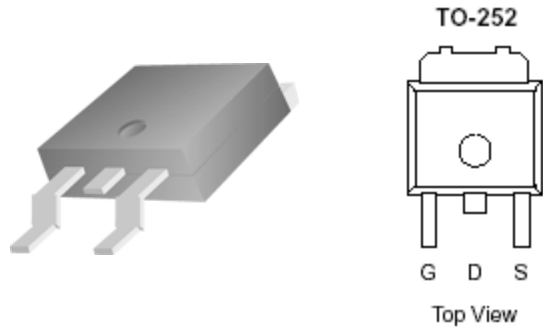


**P-Channel 20-V (D-S) MOSFET**

These miniature surface mount MOSFETs utilize High Cell Density process. Low  $r_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

- Low  $r_{DS(on)}$  Provides Higher Efficiency and Extends Battery Life
- Miniature TO-252 Surface Mount Package Saves Board Space
- High power and current handling capability
- Extended VGS range ( $\pm 25$ ) for battery pack applications

PRODUCT SUMMARY		
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (mΩ)	I <sub>D</sub> (A)
-20	118 @ V <sub>GS</sub> = -4.5V	17
	178 @ V <sub>GS</sub> = -2.5V	14



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V <sub>DS</sub>	-20	V
Gate-Source Voltage		V <sub>GS</sub>	±12	
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	17	A
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	±40	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	-30	A
Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	50	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>θJA</sub>	50	°C/W
Maximum Junction-to-Case	R <sub>θJC</sub>	3.0	°C/W

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

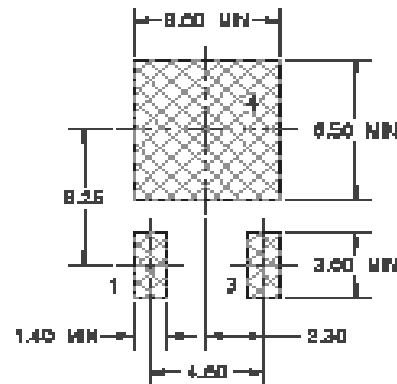
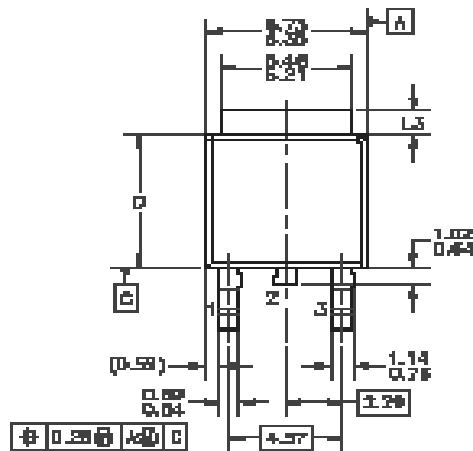
SPECIFICATIONS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
<b>Static</b>						
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 uA	-0.7			
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±25 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0 V			-1	uA
		V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55°C			-5	
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = -5 V, V <sub>GS</sub> = -4.5 V	-41			A
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -17 A			118	mΩ
		V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -14 A			178	
Forward Transconductance <sup>A</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -17 A		31		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = -41 A, V <sub>GS</sub> = 0 V		-0.7		V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -21 A		12.2		nC
Gate-Source Charge	Q <sub>gs</sub>			1.1		
Gate-Drain Charge	Q <sub>gd</sub>			1.5		
<b>Switching</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10 V, R <sub>L</sub> = 15 Ω, I <sub>D</sub> = -41 A, V <sub>GEN</sub> = -4.5 V, R <sub>G</sub> = 6Ω		15		nS
Rise Time	t <sub>r</sub>			12		
Turn-Off Delay Time	t <sub>d(off)</sub>			62		
Fall-Time	t <sub>f</sub>			46		

Notes

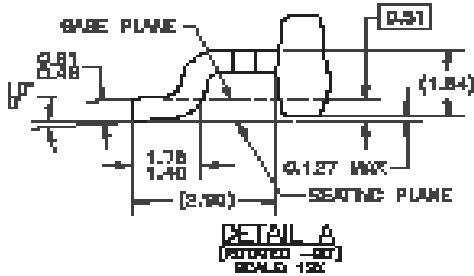
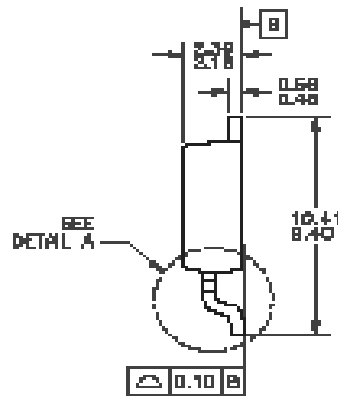
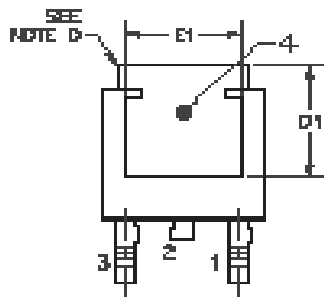
- a. Pulse test: PW ≤ 300us duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.

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# Package Information



LAND PATTERN RECOMMENDATION



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) ALL DIMENSIONS ARE IN MILLIMETERS.
  - B) THIS PACKAGE CONFORMS TO JEDEC, TO-262, ISSUE C, VARIATION AA, 30 DE, DATED NOV. 1999.
  - C) DIMENSIONING AND TOLERANCING PER ASME Y14.004-1994.
  - D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
  - E) DIMENSIONS L3,D,E1&D1 TABLE:

	OPTION AA	OPTION AB
L3	0.68-1.27	1.62-2.52
D	0.92-0.92	0.43-0.49
E1	4.32 MIN	3.81 MIN
D1	3.41 MIN	4.57 MIN